

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property
Organization
International Bureau(43) International Publication Date
29 April 2004 (29.04.2004)

PCT

(10) International Publication Number
WO 2004/035643 A1(51) International Patent Classification⁷: **C08F 283/10**,
289/00, C09D 151/08, C08F 290/06, G03F 7/00, B29C
41/00, C08L 63/00(74) Agent: RENKEMA, J.; DSM Intellectual Property, P.O.
Box 9, NL-6160 MA Geleen (NL).(21) International Application Number:
PCT/NL2003/000702

(22) International Filing Date: 16 October 2003 (16.10.2003)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
10/273,357 18 October 2002 (18.10.2002) US(81) Designated States (*national*): AE, AG, AL, AM, AT, AU,
AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU,
CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE,
GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR,
KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK,
MN, MW, MX, MZ, NI, NO, NZ, OM, PG, PH, PL, PT,
RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR,
TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.(84) Designated States (*regional*): ARIPO patent (GH, GM,
KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW),
Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM),
European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE,
ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO,
SE, SI, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM,
GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).**Published:**

— with international search report

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.(71) Applicant (*for all designated States except US*): DSM IP
ASSETS B.V. [NL/NL]; Het Overloon 1, NL-6411 TE
Heerlen (NL).

(72) Inventor; and

(75) Inventor/Applicant (*for US only*): XU, Jigeng [CN/US];
3688 Mariam Drive, Boothwyn, PA 19061 (US).

(54) Title: CURABLE COMPOSITIONS AND RAPID PROTOTYPING PROCESS USING THE SAME

(57) Abstract: The present invention provides curable compositions and rapid prototyping processes using the same. In one embodiment, the present compositions include one or more aromatic epoxies and one or more aliphatic epoxies, and, after full cure, exhibit a heat deflection temperature of at least 105°C and an elongation at break of at least 1.5%.

WO 2004/035643 A1

CURABLE COMPOSITIONS AND RAPID PROTOTYPING PROCESS USING THE
SAME

5

FIELD OF THE INVENTION

The present invention relates to curable compositions capable of providing articles having the combination of a good elongation at break and good high temperature resistance. In addition, the present invention relates to applications for
10 such compositions, such as their use in rapid prototyping processes.

BACKGROUND

In the field of curable compositions, for instance in the field of rapid prototyping compositions, high temperature resistance, elongation to break, and cure
15 speed are relevant parameters. Unfortunately, a composition providing good high temperature resistance often exhibits a poor elongation to break. One of the objectives of the present invention is to provide compositions yielding both a good high temperature resistance and a good elongation to break. Another objective is to provide compositions that furthermore have a good cure speed.

20 Examples of prior curable compositions are set forth in, for instance, U.S. Patent 5,476,748; U.S. Patent 5,707,780; U.S. Patent 5,972,563; U.S. Patent 5,981,616; U.S. Patent 6,313,188; U.S. Patent 6,368,769; European Patent Application 0360869; and Japanese Patent Application 11199647.

25 SUMMARY

The present invention provides compositions having both a good high temperature resistance and a good elongation to break. Furthermore, the present invention provides compositions that additionally have a good cure speed. Also, the present invention provides applications for the compositions, such as their use in a
30 rapid prototyping process.

In one embodiment, the present invention provides a curable composition comprising:

- (i) one or more aromatic epoxies; and
- (ii) one or more aliphatic epoxies;

wherein said composition, after full cure, has a heat deflection temperature under a pressure of 1.82 MPa of at least 105°C and an elongation at break of at least 1.5%.

5 In another embodiment, the present invention provides a curable composition having an E10 cure speed of less than 80 mJ/cm² and, after full cure, a heat deflection temperature under a pressure of 1.82 MPa of at least 125°C and an elongation at break of at least 2.5%.

Additional objects, advantages and features of the present invention are set forth in this specification, and in part will become apparent to those skilled in the art on examination of the following, or may be learned by practice of the invention. The inventions disclosed in this application are not limited to any particular set of or combination of objects, advantages and features. It is contemplated that various combinations of the stated objects, advantages and features make up the inventions disclosed in this application.

15

DETAILED DESCRIPTION

(A) Cationically curable component

The present compositions comprise at least one cationically curable component, *e.g.* at least one cyclic ether component, cyclic lactone component, cyclic acetal component, cyclic thioether component, spiro orthoester component, epoxy-functional component, and/or oxetane-functional component. Preferably, the present compositions comprise at least one component selected from the group consisting of epoxy-functional components and oxetane-functional components. Preferably, the compositions comprise, relative to the total weight of the composition, at least 20 wt% of cationically curable components, for instance at least 40 wt%, at least 60 wt%, at least 70 wt%, or at least 80 wt%. Generally, the compositions comprise, relative to the total weight of the composition, less than 99 wt% of cationically curable components, for instance less than 95 wt%, less than 90 wt%, or less than 85 wt%.

(A1) Epoxy-functional components

The present compositions preferably comprise at least one epoxy-functional component, *e.g.* an aromatic epoxy-functional component ("aromatic epoxy") and/or an aliphatic epoxy-functional component ("aliphatic epoxy"). Epoxy-functional components are components comprising one or more epoxy groups, *i.e.* one or more three-member ring structures (oxiranes) according to formula (1):

35



(1).

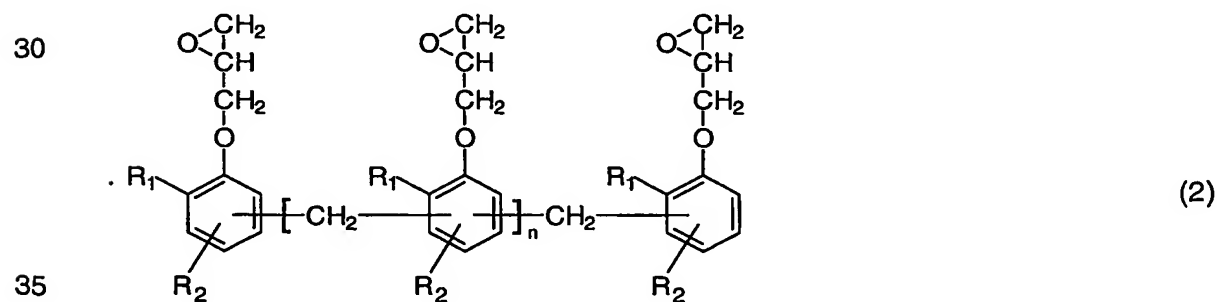
5 (A1-i) aromatic epoxies

Aromatic epoxies are components that comprise one or more epoxy groups and one or more aromatic rings. The compositions may comprise one or more aromatic epoxies, *e.g.* two or more aromatic epoxies or three or more aromatic epoxies.

10 Examples of aromatic epoxies include aromatic epoxies derived from a polyphenol, *e.g.* from bisphenols such as bisphenol A (4,4'-isopropylidenediphenol), bisphenol F (bis[4-hydroxyphenyl]methane), bisphenol S (4,4'-sulfonyldiphenol), 4,4'-cyclohexylidenebisphenol, 4,4'-biphenol, or 4,4'-(9-fluorenylidene)diphenol. The bisphenols may be alkoxyated (*e.g.* ethoxylated and/or propoxylated) and/or
15 halogenated (*e.g.* brominated). Examples of bisphenol epoxies include bisphenol diglycidyl ethers.

Further examples of aromatic epoxies include triphenylolmethane triglycidyl ether, 1,1,1-tris(*p*-hydroxyphenyl)ethane triglycidyl ether, and aromatic epoxies derived from a monophenol, *e.g.* from resorcinol (for instance resorcin diglycidyl ether) or hydroquinone (for instance hydroquinone diglycidyl ether). Another
20 example is nonylphenyl glycidyl ether.

In addition, examples of aromatic epoxies include epoxy novolacs, for instance phenol epoxy novolacs and cresol epoxy novolacs. Commercial examples of cresol epoxy novolacs include, *e.g.*, EPICLON N-660, N-665, N-667, N-670, N-673, N-
25 680, N-690, and N-695, manufactured by Dainippon Ink and Chemicals, Inc. Examples of phenol epoxy novolacs include, *e.g.*, EPICLON N-740, N-770, N-775, and N-865, manufactured by Dainippon Ink and Chemicals Inc. Examples of epoxy novolacs also include those components represented by the following formulae (2), (3), or (4):





Preferably, the present compositions comprise, relative to the total weight of the composition, at least 10wt% of one or more aromatic epoxies, *e.g.* at least 25 wt%, at least 40wt%, at least 45 wt%, at least 50 wt%, or at least 55 wt%. Generally, the present compositions will comprise, relative to the weight of the composition less than 90 wt% of one or more aromatic epoxies, for instance less than 80 wt%.

(A1-ii) aliphatic epoxies

Aliphatic epoxies are components that comprise one or more epoxy groups and are absent an aromatic ring. The compositions may comprise one or more aliphatic epoxies.

5 Examples of aliphatic epoxies include glycidyl ethers of C₂-C₃₀ alkyls; 1,2 epoxies of C₃-C₃₀ alkyls; mono and multi glycidyl ethers of aliphatic alcohols and polyols such as 1,4-butanediol, neopentyl glycol, cyclohexane dimethanol, dibromo neopentyl glycol, trimethylol propane, polytetramethylene oxide, polyethylene oxide, polypropylene oxide, glycerol, and alkoxyated aliphatic alcohols and polyols.

10 In one embodiment, it is preferred that the aliphatic epoxies comprise one or more cycloaliphatic ring structures. For instance, the aliphatic epoxies may have one or more cyclohexene oxide structures, *e.g.* two cyclohexene oxide structures. Examples of aliphatic epoxies comprising a ring structure include hydrogenated bisphenol A diglycidyl ethers, hydrogenated bisphenol F diglycidyl ethers,
15 hydrogenated bisphenol S diglycidyl ethers, bis(4-hydroxycyclohexyl)methane diglycidyl ether, 2,2-bis(4-hydroxycyclohexyl)propane diglycidyl ether, 3,4-epoxycyclohexylmethyl-3,4-epoxycyclohexanecarboxylate, 3,4-epoxy-6-methylcyclohexylmethyl-3,4-epoxy-6-methylcyclohexanecarboxylate, di(3,4-epoxycyclohexylmethyl)hexanedioate, di(3,4-epoxy-6-
20 methylcyclohexylmethyl)hexanedioate, ethylenebis(3,4-epoxycyclohexanecarboxylate), ethanedioldi(3,4-epoxycyclohexylmethyl) ether, and 2-(3,4-epoxycyclohexyl-5,5-spiro-3,4-epoxy)cyclohexane-1,3-dioxane.

 Examples of aliphatic epoxies are also listed in U.S. Patent 6,410,127, which is hereby incorporated in its entirety by reference.

25 In one embodiment, the present compositions comprise, relative to the total weight of the composition, at least 5 wt% of one or more aliphatic epoxies, for instance at least 8 wt%, at least 10wt%, or at least 12 wt%. Generally, the present compositions will comprise, relative to the total weight of the composition, less than 50 wt% of aliphatic epoxies, for instance less than 40 wt%, less than 30 wt%, less than
30 25wt%, or less than 20 wt%.

(A2) Oxetane-functional components

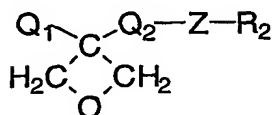
 The present compositions may comprise one or more oxetane-functional components ("oxetanes"). Oxetanes are components comprising one or
35 more oxetane groups, *i.e.* one or more four-member ring structures according to

formula (5):



(5)

5 Examples of oxetanes include components represented by the following formula (6):



(6)

10

wherein

- Q_1 represents a hydrogen atom, an alkyl group having 1 to 6 carbon atoms (such as a methyl, ethyl, propyl, or butyl group), a fluoroalkyl group having 1 to 6 carbon atoms, an allyl group, an aryl group, a furyl group, or a thienyl group;
- 15 Q_2 represents an alkylene group having 1 to 6 carbon atoms (such as a methylene, ethylene, propylene, or butylene group), or an alkylene group containing an ether linkage, for example, an oxyalkylene group, such as an oxyethylene, oxypropylene, or oxybutylene group
- Z represents an oxygen atom or a sulphur atom; and
- 20 R_2 represents a hydrogen atom, an alkyl group having 1-6 carbon atoms (e.g. a methyl group, ethyl group, propyl group, or butyl group), an alkenyl group having 2-6 carbon atoms (e.g. a 1-propenyl group, 2-propenyl group, 2-methyl-1-propenyl group, 2-methyl-2-propenyl group, 1-butenyl group, 2-butenyl group, or 3-butenyl group), an aryl group having 6-18 carbon atoms (e.g. a phenyl group, naphthyl group, anthranyl group, or phenanthryl group), a substituted or unsubstituted aralkyl group having 7-18 carbon atoms (e.g. a benzyl group, fluorobenzyl group, methoxy benzyl group, phenethyl group, styryl group, cinnamyl group, ethoxybenzyl group), an aryloxyalkyl group (e.g. a phenoxyethyl group or phenoxyethyl group), an alkylcarbonyl group having 2-6 carbon atoms (e.g. an ethylcarbonyl group, propylcarbonyl group, or butylcarbonyl group), an alkoxy carbonyl group having 2-6 carbon atoms (e.g. an ethoxycarbonyl group, propoxycarbonyl group, or butoxycarbonyl group), an N-alkylcarbamoyl group having 2-6 carbon atoms (e.g. an ethylcarbamoyl group, propylcarbamoyl group, butylcarbamoyl group, or pentylcarbamoyl group), or a polyethergroup having 2-1000 carbon atoms.

35

Preferred oxetanes include those wherein

Q₁ represents a C₁-C₄ alkyl group (e.g. an ethyl group),

Z represents an oxygen atom,

Q₂ represents a methylene group, and/or

R₂ represents a hydrogen atom, a C₁-C₈ alkyl group, or a phenyl group.

5 Some further examples of oxetanes include the following:

Oxetanes containing one oxetane ring in the molecule include, for instance, 3-ethyl-3-hydroxymethyloxetane, 3-(meth)allyloxymethyl-3-ethyloxetane, (3-ethyl-3-oxetanylmethoxy)methylbenzene, (3-ethyl-3-oxetanylmethoxy)benzene, 4-fluoro-[1-(3-ethyl-3-oxetanylmethoxy)methyl]benzene, 4-methoxy-[1-(3-ethyl-3-oxetanylmethoxy)methyl]benzene, [1-(3-ethyl-3-oxetanylmethoxy)ethyl] phenyl ether, isobutoxymethyl (3-ethyl-3-oxetanylmethyl) ether, isobornyloxyethyl (3-ethyl-3-oxetanylmethyl) ether, isobornyl (3-ethyl-3-oxetanylmethyl) ether, 2-ethylhexyl (3-ethyl-3-oxetanyl methyl) ether, ethyldiethylene glycol (3-ethyl-3-oxetanylmethyl) ether, dicyclopentadiene (3-ethyl-3-oxetanylmethyl) ether, dicyclopentenyl (3-ethyl-3-oxetanylmethyl) ether, 15 dicyclopentenyl (3-ethyl-3-oxetanylmethyl) ether, tetrahydrofurfuryl (3-ethyl-3-oxetanylmethyl) ether, tetrabromophenyl (3-ethyl-3-oxetanylmethyl) ether, 2-tetrabromophenoxyethyl (3-ethyl-3-oxetanylmethyl) ether, tribromophenyl (3-ethyl-3-oxetanylmethyl) ether, 2-tribromophenoxyethyl (3-ethyl-3-oxetanylmethyl) ether, 2-hydroxyethyl (3-ethyl-3-oxetanyl methyl) ether, 20 hydroxypropyl (3-ethyl-3-oxetanylmethyl) ether, butoxyethyl (3-ethyl-3-oxetanylmethyl) ether, pentachlorophenyl (3-ethyl-3-oxetanylmethyl) ether, pentabromophenyl (3-ethyl-3-oxetanylmethyl) ether, bornyl (3-ethyl-3-oxetanylmethyl) ether, 2-phenyl-3, 3-dimethyl-oxetane, and 2-(4-methoxyphenyl)-3, 3-dimethyl-oxetane.

Oxetanes containing two or more oxetane rings in the molecule include, for instance, 3,7-bis(3-oxetanyl)-5-oxa-nonane, 3,3'-(1,3-(2-methylenyl)propanediylbis(oxymethylene))bis-(3-ethyloxetane), 1,4-bis[(3-ethyl-3-oxetanylmethoxy)methyl]benzene, 1,2-bis[(3-ethyl-3-oxetanylmethoxy)methyl]ethane, 1,3-bis[(3-ethyl-3-oxetanylmethoxy)methyl]propane, ethylene glycol bis(3-ethyl-3-oxetanylmethyl) ether, dicyclopentenyl bis(3-ethyl-3-oxetanylmethyl) ether, triethylene glycol bis(3-ethyl-3-oxetanylmethyl) ether, tetraethylene glycol bis(3-ethyl-3-oxetanylmethyl) ether, tricyclodecanediyl dimethylene (3-ethyl-3-oxetanylmethyl) ether, trimethylolpropane tris(3-ethyl-3-oxetanylmethyl) ether, 1,4-bis(3-ethyl-3-oxetanylmethoxy)butane, 1,6-bis(3-ethyl-3-oxetanylmethoxy)hexane, pentaerythritol tris(3-ethyl-3-oxetanylmethyl) ether, pentaerythritol tetrakis(3-ethyl-3-oxetanylmethyl) ether, 35 polyethylene glycol bis(3-ethyl-3-oxetanylmethyl) ether, dipentaerythritol

hexakis(3-ethyl-3-oxetanylmethyl) ether, dipentaerythritol pentakis(3-ethyl-3-oxetanylmethyl) ether, dipentaerythritol tetrakis(3-ethyl-3-oxetanylmethyl) ether, caprolactone-modified dipentaerythritol hexakis(3-ethyl-3-oxetanylmethyl) ether, caprolactone-modified dipentaerythritol pentakis(3-ethyl-3-oxetanylmethyl) ether,
 5 ditrimethylolpropane tetrakis(3-ethyl-3-oxetanylmethyl) ether, ethoxylated bisphenol A bis(3-ethyl-3-oxetanylmethyl) ether, propoxylated bisphenol A bis(3-ethyl-3-oxetanylmethyl) ether, ethoxylated hydrogenated bisphenol A bis(3-ethyl-3-oxetanylmethyl) ether, propoxylated hydrogenated bisphenol A bis(3-ethyl-3-oxetanylmethyl) ether, ethoxylated bisphenol F (3-ethyl-3-oxetanylmethyl) ether.

10 In one embodiment, the present compositions comprise, relative to the total weight of the composition, at least 5 wt% of one or more oxetanes, *e.g.* at least 8 wt%, at least 10 wt%, at least 12 wt%, or at least 14 wt%. Generally, the present compositions comprise less than 50 wt% of oxetanes, *e.g.* less than 40 wt%, less than 35 wt%, less than 30 wt%, or less than 25 wt%.

15

(B) Free radical polymerizable components

In addition to one or more cationically curable components, the present invention may comprise one or more free radical curable components, *e.g.* one or more free radical polymerizable components having one or more ethylenically
 20 unsaturated groups, such as (meth)acrylate (*i.e.* acrylate and/or methacrylate) functional components.

Examples of monofunctional ethylenically unsaturated components include acrylamide, N,N-dimethylacrylamide, (meth)acryloylmorpholine, 7-amino-3,7-dimethyloctyl (meth)acrylate, isobutoxymethyl(meth)acrylamide, isobornyloxyethyl
 25 (meth)acrylate, isobornyl (meth)acrylate, 2-ethylhexyl (meth)acrylate, ethyldiethylene glycol (meth)acrylate, t-octyl (meth)acrylamide, diacetone (meth)acrylamide, dimethylaminoethyl (meth)acrylate, diethylaminoethyl (meth)acrylate, lauryl (meth)acrylate, dicyclopentadiene (meth)acrylate, dicyclopentenylloxyethyl (meth)acrylate, dicyclopentenyl (meth)acrylate, N,N-
 30 dimethyl(meth)acrylamidetetrachlorophenyl (meth)acrylate, 2-tetrachlorophenoxyethyl (meth)acrylate, tetrahydrofurfuryl (meth)acrylate, tetrabromophenyl (meth)acrylate, 2-tetrabromophenoxyethyl (meth)acrylate, 2-trichlorophenoxyethyl (meth)acrylate, tribromophenyl (meth)acrylate, 2-tribromophenoxyethyl (meth)acrylate, 2-hydroxyethyl (meth)acrylate, 2-hydroxypropyl (meth)acrylate, vinylcaprolactam, N-vinylpyrrolidone,
 35 phenoxyethyl (meth)acrylate, butoxyethyl (meth)acrylate, pentachlorophenyl

(meth)acrylate, pentabromophenyl (meth)acrylate, polyethylene glycol mono(meth)acrylate, polypropylene glycol mono(meth)acrylate, bornyl (meth)acrylate, and, methyltriethylene diglycol (meth)acrylate.

Examples of the polyfunctional ethylenically unsaturated components include ethylene glycol di(meth)acrylate, dicyclopentenyl di(meth)acrylate, triethylene glycol diacrylate, tetraethylene glycol di(meth)acrylate, tricyclodecanedioldimethylene di(meth)acrylate, trimethylolpropane tri(meth)acrylate, ethoxylated trimethylolpropane tri(meth)acrylate, propoxylated trimethylolpropane tri(meth)acrylate, tripropylene glycol di(meth)acrylate, neopentyl glycol di(meth)acrylate, both-terminal (meth)acrylic acid adduct of bisphenol A diglycidyl ether, 1,4-butanediol di(meth)acrylate, 1,6-hexanediol di(meth)acrylate, polyethylene glycol di(meth)acrylate, (meth)acrylate-functional pentaerythritol derivatives (e.g. pentaerythritol tri(meth)acrylate, pentaerythritol tetra(meth)acrylate, dipentaerythritol hexa(meth)acrylate, dipentaerythritol penta(meth)acrylate, or dipentaerythritol tetra(meth)acrylate), ditrimethylolpropane tetra(meth)acrylate, ethoxylated bisphenol A di(meth)acrylate, propoxylated bisphenol A di(meth)acrylate, ethoxylated hydrogenated bisphenol A di(meth)acrylate, propoxylated -modified hydrogenated bisphenol A di(meth)acrylate, and ethoxylated bisphenol F di(meth)acrylate.

In one embodiment, the present compositions comprise one or more components having at least 3 (meth)acrylate groups, for instance 3-6 (meth)acrylate groups or 5-6 (meth)acrylate groups.

If present, the compositions may comprise, relative to the total weight of the composition, at least 3 wt% of one or more free radical polymerizable components, for instance at least 5 wt% or at least 9 wt%. Generally, the compositions comprise, relative to the total weight of the composition, less than 50 wt% of free radical polymerizable components, for instance less than 35 wt%, less than 25 wt%, less than 20 wt%, or less than 15 wt%.

(C) Hydroxy-functional components

Preliminarily, hydroxy-functional components in this section (C) are understood to be absent curable groups (such as, e.g., acrylate-, epoxy-, or oxetane groups) and to be not selected from the group consisting of photoinitiators.

The present compositions may comprise one or more hydroxy-functional components. Hydroxy-functional components may be helpful in further tailoring mechanical properties of the present compositions upon cure. Hydroxy-

functional components include monols (hydroxy-functional components comprising one hydroxy group) and polyols (hydroxy-functional components comprising more than one hydroxy group).

Representative examples of hydroxy-functional components include

5 alkanols, monoalkyl ethers of polyoxyalkyleneglycols, monoalkyl ethers of alkyleneglycols, alkylene and arylalkylene glycols, such as 1,2,4-butanetriol, 1,2,6-hexanetriol, 1,2,3-heptanetriol, 2,6-dimethyl-1,2,6-hexanetriol, (2R,3R)-(-)-2-benzyloxy-1,3,4-butanetriol, 1,2,3-hexanetriol, 1,2,3-butanetriol, 3-methyl-1,3,5-pentanetriol, 1,2,3-cyclohexanetriol, 1,3,5-cyclohexanetriol, 3,7,11,15-tetramethyl-1,2,3-hexadecanetriol,

10 2-hydroxymethyltetrahydropyran-3,4,5-triol, 2,2,4,4-tetramethyl-1,3-cyclobutanediol, 1,3-cyclopentanediol, trans-1,2-cyclooctanediol, 1,16-hexadecanediol, 3,6-dithia-1,8-octanediol, 2-butyne-1,4-diol, 1,3-propanediol, 1,4-butanediol, 1,5-pentanediol, 1,6-hexanediol, 1,7-heptanediol, 1,8-octanediol, 1,9-nonanediol, 1-phenyl-1,2-ethanediol, 1,2-cyclohexanediol, 1,5-decalindiol, 2,5-dimethyl-3-hexyne-2,5-diol, 2,7-dimethyl-3,5-

15 octadiyne-2,7-diol, 2,3-butanediol, 1,4-cyclohexanedimethanol, polyoxyethylene and polyoxypropylene glycols and triols of molecular weights from about 200 to about 10,000, polytetramethylene glycols of varying molecular weight, poly(oxyethylene-oxybutylene) random or block copolymers, copolymers containing pendant hydroxy groups formed by hydrolysis or partial hydrolysis of vinyl acetate copolymers,

20 polyvinylacetal resins containing pendant hydroxyl groups; hydroxy-functional (e.g. hydroxy-terminated) polyesters and hydroxy-functional (e.g. hydroxy-terminated) polylactones, aliphatic polycarbonate polyols (e.g. an aliphatic polycarbonate diol), hydroxy-functional (e.g. hydroxy-terminated) polyethers (e.g. polytetrahydrofuran polyols having a number average molecular weight in the range of 150-4000 g/mol,

25 150-1500g/mol, or 150-750 g/mol), and combinations thereof.

In one embodiment, the compositions are absent substantial amounts of hydroxy-functional components. The absence of substantial amounts of hydroxy-functional components may decrease the hygroscopicity of the compositions and/or articles obtained therewith. For instance, the compositions may comprise, relative to

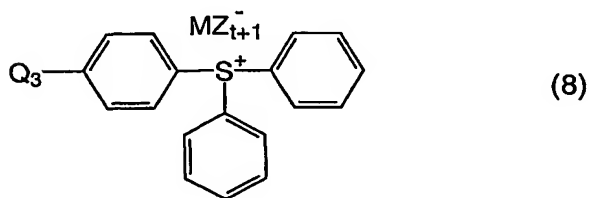
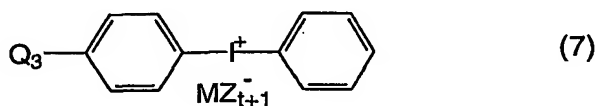
30 the total weight of the composition, less than 15 wt%, less than 10 wt%, less than 6 wt%, less than 4 wt%, less than 2 wt%, or about 0 wt% of hydroxy-functional components.

(D) Cationic photoinitiators

The present compositions preferably comprise one or more cationic photoinitiators, *i.e.* photoinitiators that, upon exposure to actinic radiation, form cations that can initiate the reactions of cationically polymerizable components, such as epoxies or oxetanes.

5 Examples of cationic photoinitiators include, for instance, onium salts with anions of weak nucleophilicity. Examples include halonium salts, iodosyl salts or sulfonium salts, such as are described in published European patent application EP 153904 and WO 98/28663, sulfoxonium salts, such as described, for example, in published European patent applications EP 35969, 44274, 54509, and 164314, or
10 diazonium salts, such as described, for example, in U.S. Patents 3,708,296 and 5,002,856. All eight of these disclosures are hereby incorporated in their entirety by reference. Other examples of cationic photoinitiators include metallocene salts, such as described, for instance, in published European applications EP 94914 and 94915, which applications are both hereby incorporated in their entirety by reference.

15 In one embodiment, the present compositions comprise one or more photoinitiators represented by the following formula (7) or (8):



25 wherein

Q_3 represents a hydrogen atom, an alkyl group having 1 to 18 carbon atoms, or an alkoxy group having 1 to 18 carbon atoms;

M represents a metal atom, *e.g.* antimony;

Z represents a halogen atom, *e.g.* fluorine; and

30 t is the valent number of the metal, *e.g.* 5 in the case of antimony.

In one embodiment, the present compositions comprise, relative to the total weight of the composition, 0.1-15 wt% of one or more cationic photoinitiators, for instance 1-10 wt%.

(E) Free radical photoinitiators

The compositions may employ one or more free radical photoinitiators. Examples of free radical photoinitiators include benzophenones (*e.g.* benzophenone, alkyl-substituted benzophenone, or alkoxy-substituted benzophenone); benzoin, *e.g.* benzoin, benzoin ethers, such as benzoin methyl ether, benzoin ethyl ether, and benzoin isopropyl ether, benzoin phenyl ether, and benzoin acetate; acetophenones, such as acetophenone, 2,2-dimethoxyacetophenone, 4-(phenylthio)acetophenone, and 1,1-dichloroacetophenone; benzil, benzil ketals, such as benzil dimethyl ketal, and benzil diethyl ketal; anthraquinones, such as 2-methylantraquinone, 2-ethylantraquinone, 2-tertbutylantraquinone, 1-chloroanthraquinone, and 2-amylantraquinone; triphenylphosphine; benzoylphosphine oxides, such as, for example, 2,4,6-trimethylbenzoyldiphenylphosphine oxide; thioxanthenes and xanthenes, acridine derivatives, phenazene derivatives, quinoxaline derivatives or 1-phenyl-1,2-propanedione-2-O-benzoyloxime, 1-aminophenyl ketones or 1-hydroxyphenyl ketones, such as 1-hydroxycyclohexyl phenyl ketone, phenyl (1-hydroxyisopropyl)ketone and 4-isopropylphenyl(1-hydroxyisopropyl)ketone, or triazine compounds, for example, 4'''-methyl thiophenyl-1-di(trichloromethyl)-3,5-S-triazine, S-triazine-2-(stilbene)-4,6-bistrichloromethyl, and paramethoxy styryl triazine.

Further suitable free radical photoinitiators include the ionic dye-counter ion compounds, which are capable of absorbing actinic rays and producing free radicals, which can initiate the polymerization of the acrylates. See, for example, published European Patent Application 223587, and U.S. Patents 4,751,102, 4,772,530 and 4,772,541, all four of which are hereby incorporated in their entirety by reference.

In one embodiment, the present compositions comprise, relative to the total weight of the composition, 0.1-15 wt% of one or more free radical photoinitiators, for instance 1-10 wt%.

(F) Additives

Additives may also be present in the composition of the invention. Stabilizers are sometimes added to the compositions in order to prevent a viscosity build-up, for instance a viscosity build-up during usage in a solid imaging process. Preferred stabilizers include those described in U.S. Patent 5,665,792, the entire disclosure of which is hereby incorporated by reference. Such stabilizers are usually hydrocarbon carboxylic acid salts of group IA and IIA metals. Most preferred examples

of these salts are sodium bicarbonate, potassium bicarbonate, and rubidium carbonate. Alternative stabilizers are polyvinylpyrrolidones and polyacrylonitriles. Other possible additives are dyes, including dyes that change color upon cure. Examples of color-changing dyes include COPIKEM 20 (3,3-bis (1-butyl -2-methyl-H-indol-3-yl) - 1-(3H)-isobenzofuranone), COPIKEM 5 (2'-di (phenylmethy) amino-6'-(diethylamino)spiro(isobenzofuran-1(3H),9'-(9H)xanthen)-3-one), COPIKEM 14 (a substituted phthalide), COPIKEM 7 (3-((4-dimethylamino)-phenyl)-3 -(1-butyl-2-methylindol-3-yl) -6-dimethylamino) -1(3H)-isobenzofuranone), and COPIKEM 37 (2-(2-octoxyphenyl)-4-(4-dimethylaminophenyl)-6-(phenyl)pyridine). If present, the amount of color-changing dyes in the compositions is, relative to the total weight of the composition, preferably at least 0.0001 wt%, for instance at least 0.0005 wt%. In one embodiment, the amount of dye is, relative to the total weight of the composition, less than 1 wt%, *e.g.* less than 0.1 wt%. Even further examples of additives include antioxidants, wetting agents, antifoaming agents, thickening agents, photosensitizers (*e.g.* *n*-ethyl carbazole, benzoperylene, 1,8-diphenyl-1,3,5,7-octatetraene, or 1,6-diphenyl-1,3,5-hexatriene), and metallic-, organic-, inorganic-, or organic-inorganic hybrid fillers (*e.g.* silica particles, glass beads, or talc). The size of the fillers may vary and can be, for instance, in the nanometer range or in the micrometer range. In one embodiment, the present compositions comprise, relative to the total weight of the composition, less than 20 wt% of fillers, *e.g.* less than 10 wt%, less than 5 wt%, or about 0 wt%. In another embodiment, the present compositions comprise, relative to the total weight of the composition, up to 90 wt% of filler, *e.g.* 20-90 wt%, 40-90 wt%, or 60-90 wt%.

25 *Physical parameters*

The present compositions, after full cure, preferably have a heat deflection temperature ("HDT") under a pressure of 1.82 MPa (264 psi) of at least 105°C, for instance at least 110°C, at least 115°C, at least 120°C, or at least 125°C. The HDT (1.82 MPa) is generally below 300°C.

30 The present compositions, after full cure, preferably have an elongation at break of at least 1.5%, for instance at least 2.0%, at least 2.5%, at least 3%, or at least 3.5%. The elongation at break is generally below 50%.

The present compositions preferably have an E10 cure speed of less than 85 mJ/cm², for instance less than 80 mJ/cm², less than 70 mJ/cm², less than 60 mJ/cm², less than 55 mJ/cm², less than 50 mJ/cm², or less than 45 mJ/cm².

The physical condition of the present compositions may vary and can be, for instance, a liquid, a gel, a paste, or a solid. If the composition is a liquid, it preferably has a viscosity, at 30°C, of less than 1000 mPas, for instance less than 750 mPas, less than 650 mPas, less than 550 mPas, less than 450 mPas, or less than 350 mPas.

The present compositions, after full cure, preferably have a tensile strength of at least 35 MPa, for instance at least 40 MPa, at least 50 MPa, at least 60 MPa, or at least 70 MPa.

The present compositions, after full cure, preferably have a Young's modulus of at least 1500 MPa, for instance at least 2000 MPa, at least 2500 MPa, at least 2750 MPa, or at least 3000 MPa.

The present compositions, after full cure, preferably have a glass transition temperature (T_g) of at least 105°C, for instance at least 110°C, at least 120°C, at least 130°C, at least 140°C, or at least 150°C. The T_g is generally below 300°C.

Applications

The present compositions may be used, for instance, as coating compositions or as compositions for preparing a three dimensional object by rapid prototyping. The compositions may be cured by heat or any suitable form of radiation, *e.g.* electron beam radiation or actinic radiation, or mixtures thereof. For instance, the composition may first be cured to a certain extent by radiation and subsequently be post-cured by heat.

Rapid prototyping, sometimes also referred to as "solid imaging" or "stereolithography", concerns the imagewise curing of successive thin layers of a curable composition to form a three-dimensional object. *See, e.g.,* U.S. Patents 4,987,044; 5,014,207; 5,474,719; 5,476,748; and 5,707,780; which are all five hereby incorporated in their entirety by reference. A rapid prototyping process may for instance be described as:

- (1) coating a layer of a composition onto a surface;
- (2) exposing said layer imagewise to actinic radiation to form an imaged cross-section;
- (3) coating a further layer of the composition onto said imaged cross-section;
- (4) exposing said further layer imagewise to actinic radiation to form an additional imaged cross-section;

- (5) repeating steps (3) and (4) a sufficient number of times in order to build up a three-dimensional article;
- (6) optionally, post-curing the three-dimensional article.

5 The following examples are given as particular embodiments of the invention and to demonstrate the practice and advantages thereof. It is to be understood that the examples are given by way of illustration and are not intended to limit the specification or the claims that follow in any manner.

10 EXAMPLES

Table 1: Glossary

Commercial Name (Supplier)	Description
EPON 825 (Resolution Performance Products)	bisphenol A diglycidyl ether (aromatic epoxy)
EPICLON N-740 (Dainippon Ink & Chemical)	phenol epoxy novolac (aromatic epoxy)
HELOXY 64 (Resolution Performance Products)	nonylphenyl glycidyl ether (aromatic epoxy)
UVACURE 1500 (UCB Radcure)	3,4-epoxy cyclohexyl methyl-3,4-epoxy cyclohexyl carboxylate (aliphatic epoxy)
UVR 6000 (Dow Chemical)	3-ethyl-3-hydroxymethyl-oxetane (oxetane)
SR-399 (Sartomer)	monohydroxy dipentaerythritol pentaacrylate
IRGACURE 184 (Ciba Geigy)	1-hydroxycyclohexyl phenyl ketone
DAROCURE 1173 (Ciba Geigy)	2-hydroxy-2-methyl-1-phenyl-1-propanone
CPI-6976 (Aceto)	mixture of triarylsulfonium hexafluoroantimonate salts
SILWET L-7600 (OSI Specialities)	surfactant
BYK-A-501 (BYK-Chemie)	defoamer
PVP (Aldrich)	stabilizer (polyvinylpyrrolidone, Mw ca. 10,000)

15 Compositions were prepared by mixing the components listed in Table 2 (Examples 1-8) and Table 3 (Comparative Examples A-B), with amounts of the components being listed in parts by weight. The thus prepared compositions were subsequently analyzed in accordance with the Test Methods described below. The test results are also listed in Tables 2 and 3.

Table 2: Examples 1-8

Ingredients	Ex. 1	Ex. 2	Ex. 3	Ex. 4	Ex. 5	Ex. 6	Ex. 7	Ex. 8
EPON 825	42	39	50	42.1	40.5	34.0	42.4	38.4
EPICLON N-740	8	16		13	12.5	13.4	12.3	17.5
HELOXY 64					3.8			
UVACURE 1500	12.5	12.5	12.5	12.5	12.0	20.2	12.5	13
UVR 6000	20	15	20	15.5	15.5	15.5	16	16.6
SR399	12	12	12	11	10.6	11.0	11	9.2
CPI 6976	4	4	4	2.8	2.7	4	4	4
IRGACURE 184	1.5	1.5	1.5	2.8	2.7	1.6		1.6
DAROCURE 1173							1.6	
SILWET L-7600	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2
BYK A501	0.02	0.02	0.02	0.02	0.02	0.02	0.02	0.02
PVP	0.005	0.005	0.005	0.005	0.005		0.005	0.005
Test results								
E _c [mJ/cm ²]	10.3	8.4	6.8	8.7	9.9	5.2	9.6	7.8
D _p [μm]	130	117	137	140	152	112	130	122
E10 [mJ/cm ²]	73.4	73.6	44.3	53.5	51.8	49.9	68.9	61.8
T _g [°C]	129.8	151	118	132	127	135	131	127
HDT (1.82 MPa) [°C]	110.7	129.3	109	125.5	119.6			
Young's modulus [MPa]	3013	3131	3000	2951	3048	3083	3138	3000
Elongation at break [%]	3.7	2.6	3.5	3.3	3.7	2.3	2.0	1.7
Tensile Strength [MPa]	71.4	60.8	71.4	68.7	75.2	55.7	49.7	46.0
Viscosity, 30°C [mPas]	334	675	275	575	520	420	490	

Table 3: Comparative Examples A and B

Ingredients	Comp. Ex. A	Comp. Ex. B
EPON 825	49.6	52.8
EPICLON N-740	16	16
UVR 6000	16	16.6
SR399	12	10.5
CPI 6976	3.6	4
IRGACURE 184	2.6	1.8
DAROCURE 1173	0.2	0.2
SILWET L-7600	0.02	0.02
BYK A501	0.005	0.005
Test results		
Ec [mJ/cm ²]	14.4	20.8
Dp [μ m]	140	140
E10 [mJ/cm ²]	88.2	126.9
T _g [°C]	123	91
Young's modulus [MPa]	2979	3028
Elongation at break [%]	2.5	3.5
Tensile Strength after [MPa]	59.6	71.6
Viscosity, 30°C [mPas]	850	

TEST METHODS

(a) Tensile Strength, Young's modulus, and Elongation at Break

Tensile data was obtained by testing tensile bars ("dogbones") made by first consecutively imaging 150µm thick layers of the composition to be tested in a rapid prototyping machine. Each cross-sectional layer of the tensile bar was given exposure sufficient to polymerize the composition at a 250 µm depth, providing approximately 100 µm of overcure or engagement cure to assure adhesion to the previously coated and exposed layer. The layers were exposed with a laser emitting in the ultraviolet (UV) region at 354.7 nm. The resulting tensile bars/dogbones were approximately 150 mm long and had a cross-section in the narrowed portion of approximately 1 cm x 1 cm. After preparation of the tensile bar in the rapid prototyping machine, the tensile bar was removed from the machine, washed with tri(propyleneglycol) methyl ether ("TPM") and isopropanol, and placed in a post-curing apparatus ("PCA" sold by 3-D Systems, 10 bulb unit using Phillips TLK/05 40W bulbs). In the PCA, the tensile bar was post-cured first by subjecting it to 60 minutes of UV radiation at room temperature. After these 60 minutes, the UV radiation was stopped and the tensile bar was subjected to 160°C for two hours. The procedure of rapid prototyping a composition and post-curing a composition in the manner just described is understood herein to result in fully cured samples. The tensile tests to determine tensile strength, Young's modulus, and elongation at break were run one day after preparation of the tensile bar and in accordance with ASTM D638, which is hereby incorporated in its entirety by reference, except that no provision was made for controlling the room temperature and humidity and the bars were not equilibrated for 2 days. The reported data is the average of three measurements.

(b) Viscosity

The composition was added to a 250-mL screw cap bottle and heated to 30°C by placing it in a 30°C bath for at least one hour. The viscosity of the composition was then determined with a Brookfield DV-II+ Viscometer employing a #3 spindle.

(c) Glass Transition Temperature (T_g)

A fully cured specimen was prepared in the same manner as described above for the preparation of a tensile bar. Part of the specimen was placed

in a TA Instruments TMA 2940 at room temperature. The specimen was then heated with a ramp of 3°C/min from room temperature to 250°C under a nitrogen purge of 60 mL/min. A graph of dimension change over temperature was generated and analyzed by using TA Instrument Universal Analysis V2.6D software, which calculated the glass transition temperature from a sudden change in the slope of the thermal expansion curve.

(d) Heat Deflection Temperature (HDT)

Fully cured specimens for determining the HDT were prepared in the same manner as the above tensile bars, except that the dimensions of the specimens for the HDT measurements were 5 inch (12.7 cm) in length and 0.5x0.5 inch (12.7mm x 12.7mm) in cross-section. The HDT (under a pressure of 1.82 MPa) of the specimens was then determined according to ASTM D648-00a Method B, which is hereby incorporated in its entirety by reference, employing an ATLAS HDV2 Automated instrument.

(e) E10, D_p, and E_c

The photoproperties E_c (mJ/cm²), D_p (μm), and E10 (mJ/cm²) represent the photoresponse (in this case thickness of layer formed) of a particular formulation to exposure by a single wavelength or range of wavelengths. In the instant Examples and Comparative Examples, at least 20 grams of composition was poured into a 100 mm diameter petri-dish and allowed to equilibrate to approximately 30°C and 30% RH. The samples were then scanned in a line-by-line fashion using a focused laser beam of approximately 100-140 mW. The laser, a frequency tripled YAG laser, had an output wavelength of 354.7 nm and was pulsed at 80 KHz. The exposures were made in a square pattern approximately 20 mm by 20 mm. Six individual exposures were made at near constant laser power but at various scan speeds. The parallel scan lines making up each exposure were drawn approximately 50 μm apart. Based upon knowledge of the diameter of the focused beam at the liquid surface, the scan speed, the laser power, and the scan spacing, the summation of exposure mJ/cm² was calculated. Each square was allowed to float on the surface of the petri-dish for approximately 15 minutes. Then the squares were blotted and a thickness measurement was taken using Mitutoyo NTO25-8"C spring loaded Absolute Digimatic calipers. When the natural log of the exposures is plotted against the measured thickness a least squares fit line can be drawn. The D_p (μm) is the slope of the least

squares fit line. The E_c (mJ/cm^2) is the X-axis crossing point ($Y=0$) of the line. And the E10 is the energy necessary to produce a layer approximately 10 mils ($254\ \mu\text{m}$) thick. In general, the lower the E10 number, the faster the photospeed of the composition.

Having described specific embodiments of the present invention, it
5 will be understood that many modifications thereof will readily be apparent to those skilled in the art, and it is intended therefore that this invention is limited only by the spirit and scope of the following claims.

CLAIMS

1. A curable rapid prototyping composition comprising:
 - (i) one or more aromatic epoxies; and
 - 5 (ii) one or more aliphatic epoxies;wherein said composition, after full cure, has a heat deflection temperature (1.82 MPa) of at least 105°C and an elongation at break of at least 1.5%.
2. The composition of claim 1, wherein said composition comprises two or more aromatic epoxies.
- 10 3. The composition according to any one of claims 1-2, wherein said composition comprises at least 25 wt%, relative to the total weight of the composition, of said one or more aromatic epoxies.
4. The composition according to any one of claims 1-2, wherein said composition comprises at least 50 wt%, relative to the total weight of the composition, of
15 said one or more aromatic epoxies.
5. The composition according to any one of claims 1-4, wherein said composition further comprises one or more oxetanes.
6. The composition according to claim 5, wherein said composition comprises 5-40 wt%, relative to the total weight of the composition, of said one or more
20 oxetanes.
7. The composition according to any one of claims 1-6, wherein said one or more aliphatic epoxies consist essentially of epoxies comprising a cycloaliphatic ring structure.
8. The composition according to any one of claims 1-7, wherein said one or more
25 aliphatic epoxies include an epoxy comprising two cyclohexene oxide structures.
9. The composition according to any one of claims 1-8, wherein said composition comprises 5-30 wt% of said one or more aliphatic epoxies.
10. The composition according to any one of claims 1-9, wherein said composition
30 comprises an epoxy having no more than one epoxy group.
11. The composition according to any one of claims 1-10, wherein said composition further comprises one or more free radical polymerizable components.

12. The composition of claim 11, wherein said one or more free radical polymerizable components include a component having 5 or 6 (meth)acrylate groups.
- 5 13. The composition according to any one of claims 11-12, wherein said composition comprises 5-25 wt%, relative to the total weight of the composition, of said one or more free radical polymerizable component.
14. The composition according to any one of claims 1-13, wherein said one or more aromatic epoxies include a phenol epoxy novolac and/or a cresol epoxy novolac.
- 10 15. The composition according to any one of claims 1-14, wherein said one or more aromatic epoxies includes a bisphenol diglycidyl ether.
16. The composition according to any one of claims 1-15, wherein said composition comprises a (meth)acrylate functional pentaerythritol derivative.
- 15 17. The composition according to any one of claims 1-16, wherein said composition further comprises a cationic photoinitiator and a free radical photoinitiator.
18. The composition according to any one of claims 1-17, wherein said composition comprises about 0-4 wt% of hydroxy-functional components that are absent a curable group and are not selected from the group consisting of photoinitiators.
- 20 19. The composition according to any one of claims 1-18, wherein said heat deflection temperature is at least 115°C.
20. The composition according to any one of claims 1-18, wherein said heat deflection temperature is at least 125°C.
- 25 21. The composition according to any one of claims 1-20, wherein said elongation to break is at least 2%.
22. The composition according to any one of claims 1-20, wherein said elongation to break is at least 3%.
23. The composition according to any one of claims 1-22, wherein said composition has an E10 cure speed of less than 80 mJ/cm².
- 30 24. The composition according to any one of claims 1-23, wherein said composition has a viscosity of less than 750 mPas at 30°C.
25. The composition according to any one of claims 1-24, wherein said composition, after full cure, has a tensile strength of at least 35 MPa.

26. The composition according to any one of claims, wherein said composition, after full cure, has a modulus of at least 2000 MPa.
27. The composition according to any one of claims 1-26, wherein said composition comprises a color-changing dye.
- 5 28. A curable composition having an E10 cure speed of less than 80 mJ/cm² and, after cure by radiation and heat, a heat deflection temperature (1.82 MPa) of at least 125°C and an elongation at break of at least 2.5%.
29. The composition according to any one of claims 1-28, wherein said composition comprises, relative to the total weight of the composition, about 0
- 10 wt% filler.
30. A rapid prototyping process comprising:
- (1) coating a layer of a composition according to any one of claims 1-29 onto a surface;
- (2) exposing said layer imagewise to actinic radiation to form an imaged
- 15 cross-section;
- (3) coating a layer of said composition according to any one of claims 1-29 onto the previously exposed imaged cross-section;
- (4) exposing said layer from step (3) imagewise to actinic radiation to form an additional imaged cross-section;
- 20 (5) repeating steps (3) and (4) a sufficient number of times to form a three-dimensional article.
31. An article obtainable by the process of claim 30.
32. Use of a curable rapid prototyping composition comprising one or more aromatic epoxies, one or more aliphatic epoxies for making a three
- 25 dimensional article, whereby the article has a heat deflection temperature (at 1.82 MPa) of at least 105°C and an elongation at break of at least 1.5%.
33. Use according to claim 32, whereby has a heat deflection temperature (1.82 MPa) of at least 125 °C.
34. Use according to claims 32 or 33, wherein the article has an elongation at
- 30 break of at least 2.5%.

INTERNATIONAL SEARCH REPORT

International application No
PCT/NL 03/00702

A. CLASSIFICATION OF SUBJECT MATTER

IPC 7 C08F283/10 C08F289/00 C09D151/08 C08F290/06 G03F7/00
B29C41/00 C08L63/00

According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)

IPC 7 C08F C09D G03F B29C C08L C09J A61K

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Electronic data base consulted during the international search (name of data base and, where practical, search terms used)

EPO-Internal, WPI Data, PAJ

C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category *	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
X	WO 97 42549 A (DSM NV) 13 November 1997 (1997-11-13)	1-4, 7-34
Y	* abstract ; claims 1-4, 11 ; page 5, line 15 - page 7, line 35 ; page 2, line 29 - page 4, line 13 ; examples I - IV ; examples * page 8, line 1 - page 16, line 35 ; claims 12-14	5, 6
X	US 5 707 780 A (CASPAR JONATHAN V ET AL) 13 January 1998 (1998-01-13) cited in the application * abstract ; claims 1, 2 ; column 4, line 54-58, 61-67 ; column 5, line 5-8 * column 3, line 1 - column 9, line 63	1, 3, 4, 7-15, 17, 19-26, 28-34

☒ Further documents are listed in the continuation of box C.

☒ Patent family members are listed in annex.

* Special categories of cited documents :

- *A* document defining the general state of the art which is not considered to be of particular relevance
- *E* earlier document but published on or after the international filing date
- *L* document which may throw doubts on priority claim(s) or which is cited to establish the publication date of another citation or other special reason (as specified)
- *O* document referring to an oral disclosure, use, exhibition or other means
- *P* document published prior to the international filing date but later than the priority date claimed

- *T* later document published after the international filing date or priority date and not in conflict with the application but cited to understand the principle or theory underlying the invention
- *X* document of particular relevance; the claimed invention cannot be considered novel or cannot be considered to involve an inventive step when the document is taken alone
- *Y* document of particular relevance; the claimed invention cannot be considered to involve an inventive step when the document is combined with one or more other such documents, such combination being obvious to a person skilled in the art
- *Z* document member of the same patent family

Date of the actual completion of the international search

7 January 2004

Date of mailing of the international search report

15/01/2004

Name and mailing address of the ISA

European Patent Office, P.B. 5818 Patentlaan 2
NL - 2280 HV Rijswijk
Tel (+31-70) 340-2040, Tx. 31 651 epo nl,
Fax: (+31-70) 340-3016

Authorized officer

Hammond, A

INTERNATIONAL SEARCH REPORT

Internatio pplication No
PCT/NL 03/00702

C.(Continuation) DOCUMENTS CONSIDERED TO BE RELEVANT

Category *	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
X	US 5 476 748 A (SCHULTHESS ADRIAN ET AL) 19 December 1995 (1995-12-19) cited in the application * claim 1 ; column 4, line 7-9 ; column 3, line 24-31 ; column 2, line 42-43 * column 2, line 21 -column 11, line 35; claims 19-22	1,3,4,7, 8,11,13, 14,17-34
X	US 5 972 563 A (SCHULTHESS ADRIAN ET AL) 26 October 1999 (1999-10-26) cited in the application * abstract ; claims 1-13 ; column 4, line 25-26 ; column 3, line 38-49 ; column 2, line 57-61 * column 2, line 16 -column 14, line 63	1,3,4,7, 8,11,13, 14,17-34
Y	EP 0 848 294 A (JAPAN SYNTHETIC RUBBER CO LTD ;JAPAN FINE COATINGS CO LTD (JP); DS) 17 June 1998 (1998-06-17) * abstract ; claims 1,6 ; page 10, line 1* page 3, line 25 -page 15, line 16	5,6
A	PATENT ABSTRACTS OF JAPAN vol. 1999, no. 12, 29 October 1999 (1999-10-29) & JP 11 199647 A (TEIJIN SEIKI CO LTD), 27 July 1999 (1999-07-27) * WPI and PAJ abstracts *	5,6
A	EP 0 938 026 A (JSR CORP ;JAPAN FINE COATINGS CO LTD (JP); DSM NV (NL)) 25 August 1999 (1999-08-25) abstract; claims 1-20	1-34
A	EP 0 360 869 A (ASAHI DENKA KOGYO KK) 4 April 1990 (1990-04-04) cited in the application abstract; claims 1-7	1-34
A	WO 01 12679 A (DELTAMED MEDIZINPRODUKTE GMBH ;ZIMMERMANN MICHAEL (DE)) 22 February 2001 (2001-02-22) abstract; claims 1-25	1-34
P,A	WO 03 080755 A (MASE MASAHITO ;JSR CORP (JP); KOMIYA ZEN (JP); YOSHIZAWA JUNJI (JP) 2 October 2003 (2003-10-02) * abstract ; claims 1-3 * page 2, line 25 -page 9, line 26	1-34

INTERNATIONAL SEARCH REPORT

Int ... on on patent family members

International application No

PCT/NL 03/00702

Patent document cited in search report		Publication date	Patent family member(s)	Publication date
WO 9742549	A	13-11-1997	AU 2653497 A DE 69703205 D1 DE 69703205 T2 EP 0897558 A1 JP 2000509743 T WO 9742549 A1 US 6251557 B1	26-11-1997 02-11-2000 26-04-2001 24-02-1999 02-08-2000 13-11-1997 26-06-2001
US 5707780	A	13-01-1998	DE 69629686 D1 EP 0830641 A1 JP 11507090 T WO 9641239 A1	02-10-2003 25-03-1998 22-06-1999 19-12-1996
US 5476748	A	19-12-1995	AT 151085 T AU 658780 B2 AU 5252493 A CA 2111718 A1 DE 59306034 D1 EP 0605361 A2 ES 2100513 T3 JP 3203461 B2 JP 6228413 A	15-04-1997 27-04-1995 30-06-1994 22-06-1994 07-05-1997 06-07-1994 16-06-1997 27-08-2001 16-08-1994
US 5972563	A	26-10-1999	AU 3157997 A CA 2211628 A1 EP 0822445 A1 JP 10087791 A AT 191090 T AU 716984 B2 DE 59701299 D1 ES 2144836 T3	05-02-1998 29-01-1998 04-02-1998 07-04-1998 15-04-2000 16-03-2000 27-04-2000 16-06-2000
EP 0848294	A	17-06-1998	JP 10168165 A US 5981616 A DE 69706816 D1 DE 69706816 T2 EP 0848294 A1 US 6365644 B1	23-06-1998 09-11-1999 25-10-2001 25-04-2002 17-06-1998 02-04-2002
JP 11199647	A	27-07-1999	NONE	
EP 0938026	A	25-08-1999	JP 11228610 A JP 11240939 A JP 11310626 A EP 0938026 A1 US 6287745 B1 US 2002048717 A1	24-08-1999 07-09-1999 09-11-1999 25-08-1999 11-09-2001 25-04-2002
EP 0360869	A	04-04-1990	JP 1213304 A JP 8026121 B JP 2028261 A JP 2590215 B2 JP 2080422 A JP 2604438 B2 JP 2080423 A JP 2538652 B2 DE 68928521 D1 DE 68928521 T2	28-08-1989 13-03-1996 30-01-1990 12-03-1997 20-03-1990 30-04-1997 20-03-1990 25-09-1996 12-02-1998 16-04-1998

INTERNATIONAL SEARCH REPORT

Information on patent family members

International application No

PCT/NL 03/00702

Patent document cited in search report		Publication date	Patent family member(s)	Publication date
EP 0360869	A		EP 0360869 A1	04-04-1990
			AT 161860 T	15-01-1998
			WO 8907620 A1	24-08-1989
			US 5434196 A	18-07-1995
			US 5525645 A	11-06-1996
WO 0112679	A	22-02-2001	DE 19938463 A1	22-02-2001
			DE 19950284 A1	26-04-2001
			WO 0112679 A1	22-02-2001
			EP 1203033 A1	08-05-2002
			JP 2003507499 T	25-02-2003
WO 03080755	A	02-10-2003	JP 2003277696 A	02-10-2003
			WO 03080755 A2	02-10-2003